



Material Content Data Sheet



Sales Product Name	TLE4254EJ S			Issued	19. January 2018			
MA#	MA001674786							
Package	PG-DSO-8-27			Weight*	84.19 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.779	2.11	2.11	21125	21125
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		108	
	non noble metal	zinc	7440-66-6	0.036	0.04		432	
	non noble metal	iron	7439-89-6	0.728	0.86		8643	
wire	non noble metal	copper	7440-50-8	29.548	35.09	36.00	350944	360127
	noble metal	gold	7440-57-5	0.132	0.16	0.16	1566	1566
	encapsulation	organic material	carbon black	1333-86-4	0.099	0.12		1173
encapsulation	plastics	epoxy resin	-	4.543	5.40		53958	
	inorganic material	silicondioxide	60676-86-0	44.738	53.13	58.65	531366	586497
leadfinish	non noble metal	tin	7440-31-5	0.695	0.83	0.83	8256	8256
plating	noble metal	silver	7440-22-4	0.725	0.86	0.86	8605	8605
glue	plastics	epoxy resin	-	0.291	0.35		3456	
	noble metal	silver	7440-22-4	0.873	1.04	1.39	10368	13824
*deviation	< 10%			Sum in total:		100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com